



## Single Phase 1.0Amp Glass passivated Bridge Rectifiers

MBS

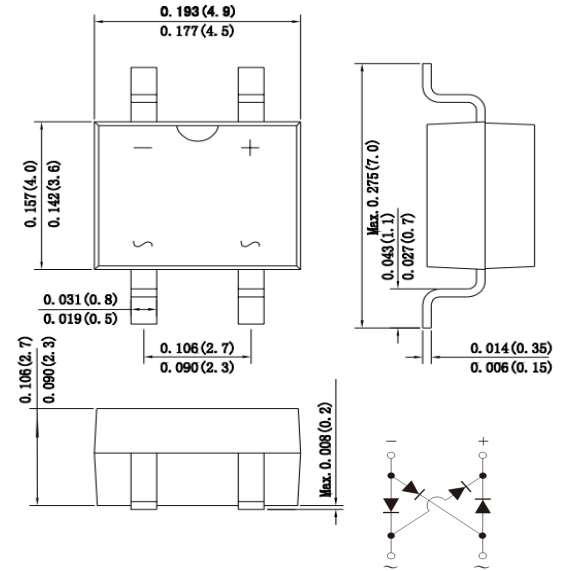


### Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Glass passivated junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed  
260°C/10 seconds at terminals

### Mechanical Data

- Case : Molded plastic body
- Terminals : Solder plated, solderable per MIL-STD-750,Method 2026
- Polarity : Polarity symbol marking on body
- Mounting Position : Any
- Weight : 0.004 ounces/0.118 gram



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbols	MB05S	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	Units
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$ On glass-epoxy P.C.B (Note 1)	$I_{(AV)}$	1.0							A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	35.0							A
Rating for fusing ( $t=8.3\text{ms}$ , $T_a=25^\circ\text{C}$ )	$I^2t$	5.08							$\text{A}^2\text{s}$
Maximum instantaneous forward voltage at 1.0A	$V_F$	1.0							V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	$I_R$	2.0 200							$\mu\text{A}$
Typical junction capacitance (Note 2)	$C_J$	18.0							pF
Typical thermal resistance	$R_{qJA}$	72.0							$^\circ\text{C}/\text{W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

Note:1.Mounted on glass epoxy PC board with 1.3\*1.3mm solder pad

2.Measured at 1MHz and applied reverse voltage of 4.0V D.C.



Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

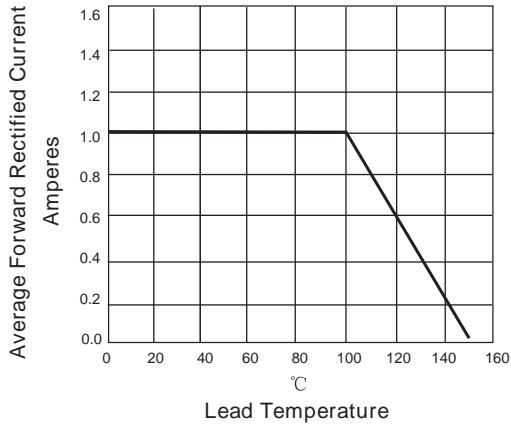


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

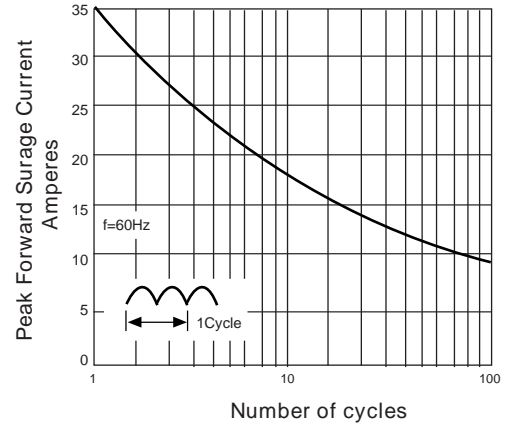


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

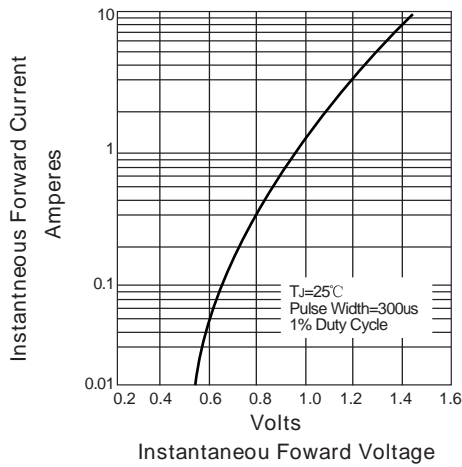
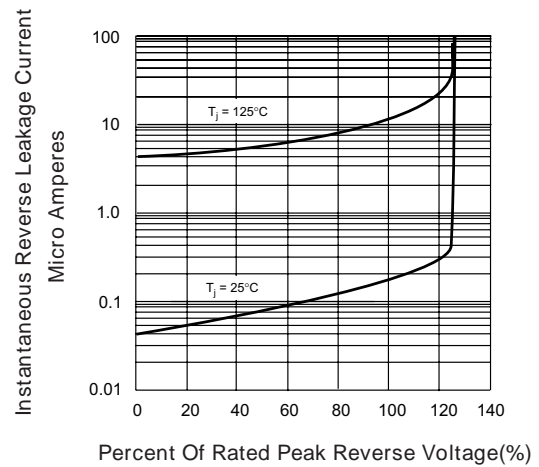
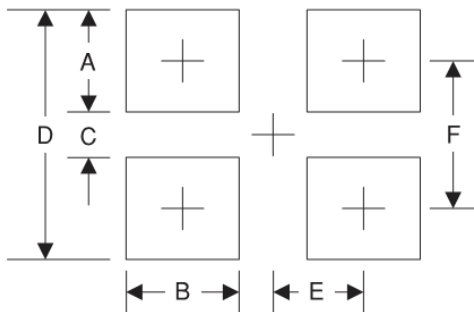


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



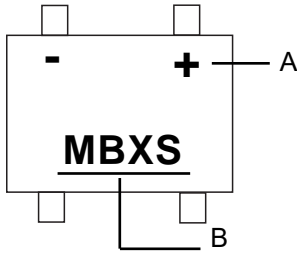
Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.7	0.067
B	1.0	0.039
C	4.40	0.173
D	8.10	0.319
E	1.25	0.049
F	6.30	0.248

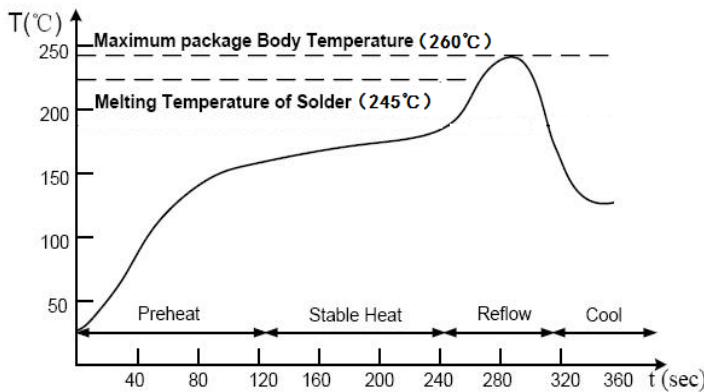


Marking



Symbol	Explanation
A	Polarity Symbol
B	Product Name, X: 05,1.....10

Suggested Soldering Temperature Profile

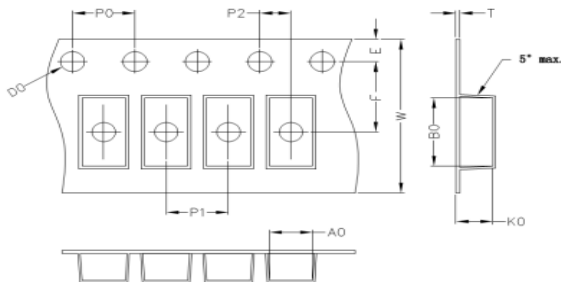


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 260°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	B0	K0	D0	E	F
5.10	7.20	2.88	1.55	1.75	5.50
P0	P1	P2	T	W	Tolerance
4.0	8.0	2.0	0.25	12	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
MBS	13'	330	3	338	6	365*365*360	48